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DST3946DPJ

#### 40V COMPLEMENTARY NPN/PNP SMALL SIGNAL TRANSISTOR IN SOT963

#### **Features**

- BV<sub>CEO</sub> > 40V
- I<sub>C</sub> = 200mA Collector Current
- SOT963 Ultra Small Package of 1mm<sup>2</sup> Footprint
- Epitaxial Planar Die Construction
- Ideally Suited for Automated Assembly Processes
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

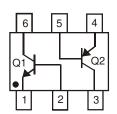
### **Mechanical Data**

- Case: SOT963
- Case Material: Molded Plastic "Green" Molding Compound;
  UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads;
  Solderable per MIL-STD-202, Method 208@3
- Weight: 0.0027 grams (Approximate)

SOT963



Top View



Top View Device Schematic and Pin-Out

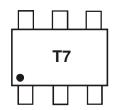
#### Ordering Information (Note 4)

Product	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
DST3946DPJ-7	T7	7	8	10,000
DST3946DPJ-7B	T7	7	8	10,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/ quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

### **Marking Information**



T7 = Product Type Marking Code



# Absolute Maximum Ratings - NPN (Q1) (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	$V_{CBO}$	60	V
Collector-Emitter Voltage	$V_{CEO}$	40	V
Emitter-Base Voltage	$V_{EBO}$	6.0	V
Collector Current	Ic	200	mA

### Absolute Maximum Ratings - PNP (Q2) (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	$V_{CBO}$	-40	V
Collector-Emitter Voltage	$V_{CEO}$	-40	V
Emitter-Base Voltage	$V_{EBO}$	-5.0	V
Collector Current	lc	-200	mA

### **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	$P_D$	300	mW
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	417	°C/W
Operating and Storage Temperature Range	$T_{J}, T_{STG}$	-55 to +150	°C

Note: 5. Device mounted on FR-4 PCB with minimum recommended pad layout.

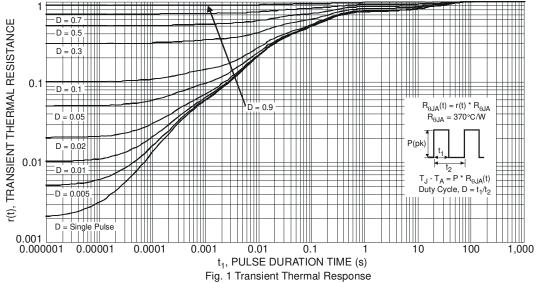
### ESD Rating (Note 6)

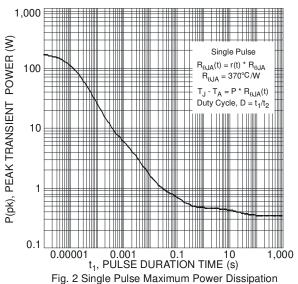
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	200	V	В

Note: 6. Refer to JEDEC specification JESD22-A114 and JESD22-A115.



## **Thermal Characteristics and Derating Information**





0.4 P<sub>D</sub>, POWER DISSIPATION (W) 1.0 2.0 8.0 0 60 80 100 120 140 160 T<sub>A</sub>, AMBIENT TEMPERATURE (°C)

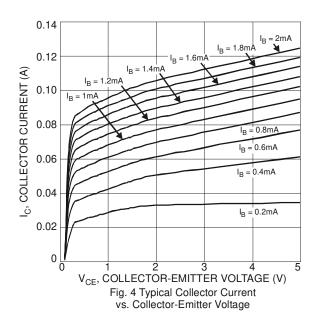
Fig. 3 Power Dissipation vs. Ambient Temperature

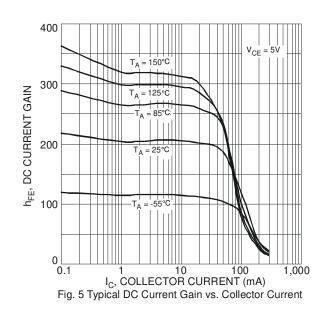


## Electrical Characteristics - NPN (Q1) (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)					
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	60		V	$I_C = 10\mu A, I_E = 0$
Collector-Emitter Breakdown Voltage (Note 7)	$BV_CEO$	40		V	$I_C = 1.0 \text{mA}, I_B = 0$
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	6.0	_	V	$I_E = 10\mu A, I_C = 0$
Collector Cutoff Current	I <sub>CEX</sub>	_	50	nA	$V_{CE} = 30V$ , $V_{EB(OFF)} = 3.0V$
Base Cutoff Current	I <sub>BL</sub>	_	50	nA	$V_{CE} = 30V, V_{EB(OFF)} = 3.0V$
ON CHARACTERISTICS (Note 7)					
DC Current Gain	h <sub>FE</sub>	40 70 100 60 30	300 —	_	$\begin{split} & I_C = 100 \mu A, \ V_{CE} = 1.0 V \\ & I_C = 1.0 mA, \ V_{CE} = 1.0 V \\ & I_C = 10 mA, \ V_{CE} = 1.0 V \\ & I_C = 50 mA, \ V_{CE} = 1.0 V \\ & I_C = 100 mA, \ V_{CE} = 1.0 V \end{split}$
Collector-Emitter Saturation Voltage	V <sub>CE(SAT)</sub>	_	0.20 0.30	V	$I_C = 10$ mA, $I_B = 1.0$ mA $I_C = 50$ mA, $I_B = 5.0$ mA
Base-Emitter Saturation Voltage	V <sub>BE(SAT)</sub>	0.65	0.85 0.95	V	$I_C = 10\text{mA}, I_B = 1.0\text{mA}$ $I_C = 50\text{mA}, I_B = 5.0\text{mA}$
SMALL SIGNAL CHARACTERISTICS					
Output Capacitance	$C_{OBO}$	_	4.0	pF	$V_{CB} = 5.0V$ , $f = 1.0MHz$ , $I_E = 0$
Input Capacitance	C <sub>IBO</sub>	_	8.5	pF	$V_{EB} = 0.5V$ , $f = 1.0MHz$ , $I_{C} = 0$
Input Impedance	h <sub>IE</sub>	1.0	10	kΩ	
Voltage Feedback Ratio	h <sub>RE</sub>	0.5	8.0	x 10 <sup>-4</sup>	$V_{CE} = 10V, I_{C} = 1.0mA,$
Small Signal Current Gain	h <sub>FE</sub>	100	400	_	f = 1.0kHz
Output Admittance	h <sub>OE</sub>	1.0	40	μs	
Current Gain-Bandwidth Product	f <sub>T</sub>	300	_	MHz	V <sub>CE</sub> = 20V, I <sub>C</sub> = 10mA, f = 100MHz
SWITCHING CHARACTERISTICS					
Delay Time	t <sub>D</sub>	_	35	ns	$V_{CC} = 3.0V, I_{C} = 10mA,$
Rise Time	t <sub>R</sub>	_	35	ns	$V_{BE(OFF)} = -0.5V, I_{B1} = 1.0mA$
Storage Time	ts	_	200	ns	$V_{CC} = 3.0V, I_{C} = 10mA,$
Fall Time	t <sub>F</sub>		50	ns	$I_{B1} = -I_{B2} = 1.0 \text{mA}$

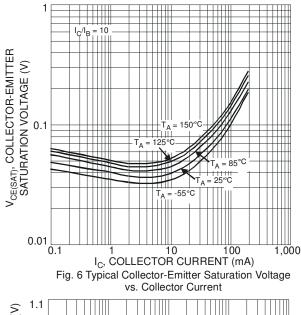
Note: 7. Short duration pulse test used to minimize self-heating effect.

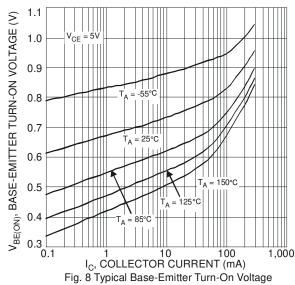


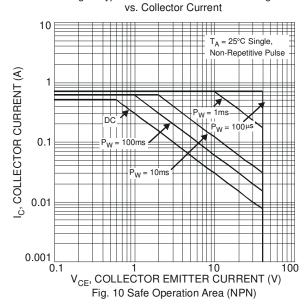












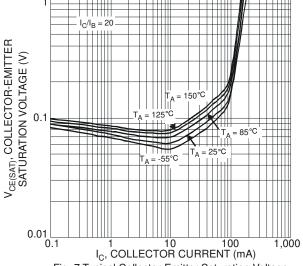


Fig. 7 Typical Collector-Emitter Saturation Voltage vs. Collector Current

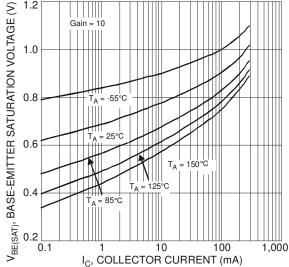


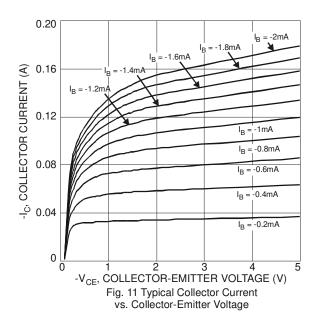
Fig. 9 Typical Base-Emitter Saturation Voltage vs. Collector Current

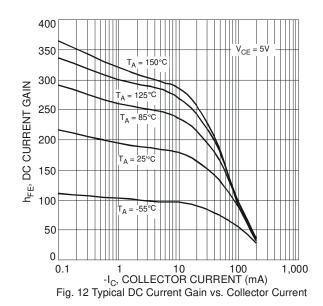


# Electrical Characteristics - PNP (Q2) ( $@T_A = +25$ °C, unless otherwise specified.)

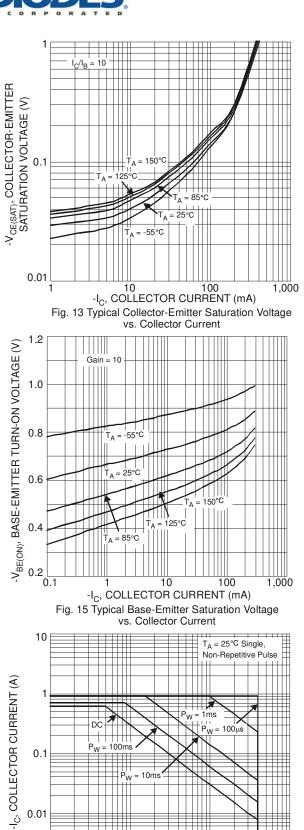
Characteristic	Symbol	Min	Max	Unit	Test Condition	
OFF CHARACTERISTICS	OFF CHARACTERISTICS					
Collector-Base Breakdown Voltage	$BV_{CBO}$	-40	_	V	$I_C = -10\mu A, I_E = 0$	
Collector-Emitter Breakdown Voltage (Note 8)	$BV_{CEO}$	-40	_	V	$I_C = -1.0 \text{mA}, I_B = 0$	
Emitter-Base Breakdown Voltage	$BV_{EBO}$	-5.0	_	V	$I_E = -10\mu A, I_C = 0$	
Collector Cutoff Current	I <sub>CEX</sub>	_	-50	nA	$V_{CE} = -30V, V_{EB(OFF)} = -3.0V$	
Collector Cuton Current	I <sub>CBO</sub>	_	-50	nA	$V_{CE} = -30V, I_{E} = 0$	
Base Cutoff Current	$I_{BL}$	_	-50	nA	$V_{CE} = -30V, V_{EB(OFF)} = -3.0V$	
ON CHARACTERISTICS (Note 8)						
		60	_		$I_C = -100 \mu A$ , $V_{CE} = -1.0 V$	
		80	_		$I_C = -1.0 \text{mA}, V_{CE} = -1.0 \text{V}$	
DC Current Gain	h <sub>FE</sub>	100	300	_	$I_C = -10 \text{mA}, V_{CE} = -1.0 \text{V}$	
		60	_		$I_C = -50 \text{mA}, V_{CE} = -1.0 \text{V}$	
		30	_		$I_C = -100 \text{mA}, V_{CE} = -1.0 \text{V}$	
Collector-Emitter Saturation Voltage	V <sub>CE(SAT)</sub>	-0.25 -0.40	-0.25		$I_C = -10mA$ , $I_B = -1.0mA$	
Concetor Emitter Cataration Voltage	V CE(SAT)		-0.40		$I_C = -50 \text{mA}, I_B = -5.0 \text{mA}$	
Base-Emitter Saturation Voltage	V <sub>BE(SAT)</sub>	-0.65	-0.85	V	$I_C = -10mA$ , $I_B = -1.0mA$	
ŭ		_	-0.95	•	$I_C = -50 \text{mA}, I_B = -5.0 \text{mA}$	
SMALL SIGNAL CHARACTERISTICS					T	
Output Capacitance	C <sub>OBO</sub>	_	4.5	pF	$V_{CB} = -5.0V$ , $f = 1.0MHz$ , $I_E = 0$	
Input Capacitance	C <sub>IBO</sub>	_	10	pF	$V_{EB} = -0.5V$ , $f = 1.0MHz$ , $I_{C} = 0$	
Input Impedance	h <sub>IE</sub>	2.0	12	kΩ		
Voltage Feedback Ratio	$h_{RE}$	0.1	10	x 10 <sup>-4</sup>	$V_{CE} = -10V, I_{C} = -1.0mA,$	
Small Signal Current Gain	h <sub>FE</sub>	100	400	_	f = 1.0kHz	
Output Admittance	h <sub>OE</sub>	3.0	60	μS		
Current Gain-Bandwidth Product	f <sub>T</sub>	300	_	MHz	$V_{CE} = -20V, I_{C} = -10mA,$ f = 100MHz	
SWITCHING CHARACTERISTICS						
Delay Time	$t_D$	_	35	ns	$V_{CC} = -3.0V, I_{C} = -10mA,$	
Rise Time	t <sub>R</sub>		35	ns	$V_{BE(OFF)} = 0.5V, I_{B1} = -1.0mA$	
Storage Time	ts	_	225	ns	$V_{CC} = -3.0V$ , $I_{C} = -10mA$ ,	
Fall Time	t <sub>F</sub>	_	75	ns	$I_{B1} = -I_{B2} = -1.0 \text{mA}$	

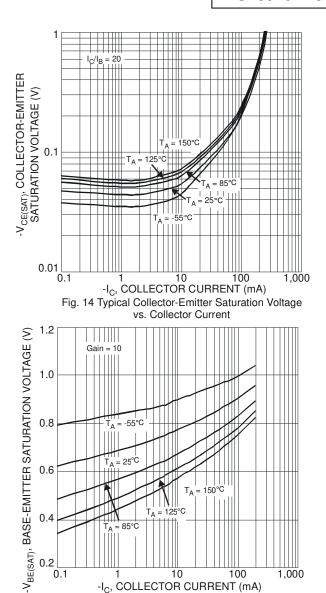
Note: 8. Short duration pulse test used to minimize self-heating effect.











-I<sub>C</sub>, COLLECTOR CURRENT (mA) Fig. 16 Typical Base-Emitter Saturation Voltage vs. Collector Current

10

= 85°C

0.4

0.1

0.1

0.001

= 100ms

P<sub>W</sub> = 10ms

-V<sub>CE</sub>, COLLECTOR EMITTER CURRENT (V) Fig. 17 Safe Operation Area (PNP)

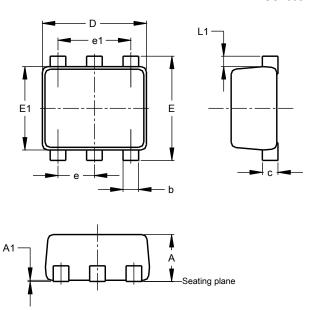
100



# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### SOT963

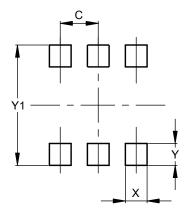


SOT963					
Dim	Min	Max	Тур		
Α	0.40	0.50	0.45		
<b>A</b> 1	0.00	0.05			
Ь	0.10	0.20	0.15		
C	0.120	0.180	0.150		
D	0.95	1.05	1.00		
Е	0.95	1.05	1.00		
E1	0.75	0.85	0.80		
е			0.35		
e1			0.70		
L1	0.05	0.15	0.10		
All Dimensions in mm					

## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### SOT963



Dimensions	Value (in mm)		
С	0.350		
Х	0.200		
Υ	0.200		
Y1	1.100		



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